

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	434	interposer with capacit\$5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:31
L2	389	L1 and (IC integrated adj circuit chip die wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:31
L3	302	L2 and (bump solder)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:31
L4	160	L2 and (bump solder)	USPAT	OR	ON	2005/12/12 21:31
L5	3	("5903050" "5937493" "6384468").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:31
L6	54	("5519576" "5672909" "5691568").PN. OR ("5903050").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:31
L7	37	("4225468" "4300115" "4332341" "4626804" "4654628" "4658234" "4712161" "4945399" "5216404" "5379190" "5539186" "5557502" "5621619" "5629838" "5635767" "5636099" "5661450" "5726485" "5729438" "5745334" "5760662" "5796587" "5870274" "5903050" "5923077" "5977863" "6005777" "6097277" "6103146" "6124634").PN. OR ("6326677").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:31
L8	61	teflon with elasticity with modul\$5	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:31
L9	0	teflon near2 "Young's" adj modulus	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:31
L10	0	teflon near2 Young\$3 adj modulus	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:31
L11	124730	teflon wiht Young\$3 adj modulus	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:31
L12	16	teflon with Young\$3 adj modulus	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:31

L13	923	silicon with Young\$3 adj modulus	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:31
L14	71	silicon near2 Young\$3 adj modulus	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:31
L15	20	("6222246").URPN.	USPAT	OR	ON	2005/12/12 21:31
L16	46165	layer near2 capacit\$5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:31
L17	19337	L16 and (IC integrated adj circuit chip die wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:31
L18	26	interposer with L16	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:31
L19	32988	film near2 capacit\$5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:31
L20	24	interposer with L19	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:31
L21	22859	substrate near2 capacit\$5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:31
L22	6587	substrate with L16	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:31
L23	3718	L22 and (IC integrated adj circuit chip die wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:31
L24	197	interposer with capacit\$5	USPAT	OR	ON	2005/12/12 21:31

L25	1	capacitive adj layer with interposer	USPAT	OR	ON	2005/12/12 21:31
L26	2	capacitive adj layer with interposer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:31
L27	4	capacitive near2 layer with interposer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:31
L28	55	("4202007" "4322778" "4328530" "4349862" "4489364" "4688151" "4744008" "4803595" "4811082" "4866507" "4926241").PN. OR ("5177594").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:31
L29	1	"5177594".PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:31
L30	1	L29 AND capac\$8	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:31
L31	55	("4202007" "4322778" "4328530" "4349862" "4489364" "4688151" "4744008" "4803595" "4811082" "4866507" "4926241").PN. OR ("5177594").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:31
L32	21344	motherboard	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:31
L33	31	motherboard with PCB WITH interposer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:31
L34	263	motherboard WITH interposer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:31
L35	98	motherboard WITH interposer	USPAT	OR	ON	2005/12/12 21:31
L36	0	motherboard WITH leve	USPAT	OR	ON	2005/12/12 21:31
L37	346	motherboard WITH level	USPAT	OR	ON	2005/12/12 21:31
L38	0	mother adj board WITH last with level	USPAT	OR	ON	2005/12/12 21:31
L39	8	mother adj board WITH last	USPAT	OR	ON	2005/12/12 21:31
L40	1459	motherboard and "257"/\$.ccls.	USPAT	OR	ON	2005/12/12 21:31

L41	184	L40 and interposer	USPAT	OR	ON	2005/12/12 21:31
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